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Thermophysics and Heat Transfer for Aerospace Applications

Guest Editor:

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Deadline for manuscript submissions:

closed (20 March 2023)

Message from the Guest Editor

The motivation for this Special Issue is to present a series of research articles in various areas of both experimental, numerical and theoretical heat transfer and fluid dynamics studies (and not only) for aerospace applications. Heat exchangers to cool electronic components, design of the thermal protection for a spacecraft, study of the fluid-structure thermal interaction or energy production are topics to face on an aerospace mission. Furthermore, in the recent years new materials are emerging in similar applications for thermal protections, sensors, actuators..... Based on your previous valuable work, we invite you to participate in this Special Issue by submitting a review or research article.











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Editor-in-Chief

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Message from the Editor-in-Chief

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